Zibo Seno Electronic Engineering Co., Ltd.

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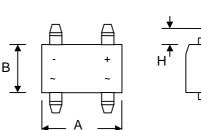


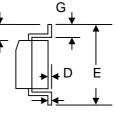
RMB05S – RMB10S 🕲

0.8A FAST RECOVERY SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material UL Flammability 94V-O





Dim

Α

В

С

D

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MB-S

Min

4.50

3.60

0.15

6.40

0.50

1.30

2.30

2.30

All Dimensions in mm

BOHS

Max

4.95

4.10

0.35

0.20

7.00

1.10

1.70

2.70

2.70

3.00

Mechanical Data

- Case: MB-S, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Weight: 0.22 grams (approx.)
- Mounting Position: Any
- Marking: Type Number
- Lead Free: For RoHS / Lead Free Version

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	RMB 05S	RMB 1S	RMB 2S	RMB 4S	RMB 6S	RMB 8S	RMB 10S	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	Vrrm Vrwm Vr	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	VR(RMS)	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1) $@T_A = 40^{\circ}C$ Average Rectified Output Current (Note 2) $@T_A = 40^{\circ}C$	lo	0.5 0.8							А
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	30							A
I ² t Rating for Fusing (t < 8.3ms)	l ² t	5.0						A ² s	
Forward Voltage per element $@I_F = 0.8A$	Vfm	1.3							V
Peak Reverse Current $@T_A = 25^{\circ}C$ At Rated DC Blocking Voltage $@T_A = 125^{\circ}C$	IRM	5.0 500							μA
Reverse Recovery Time (Note 4)	trr		150 250 500				500	nS	
Typical Junction Capacitance per leg (Note 3)	Cj	13						pF	
Typical Thermal Resistance per leg (Note 1)	RθJA RθJL	62.5 25							°C/W
Operating and Storage Temperature Range	Тј, Тѕтс	-55 to +150							°C

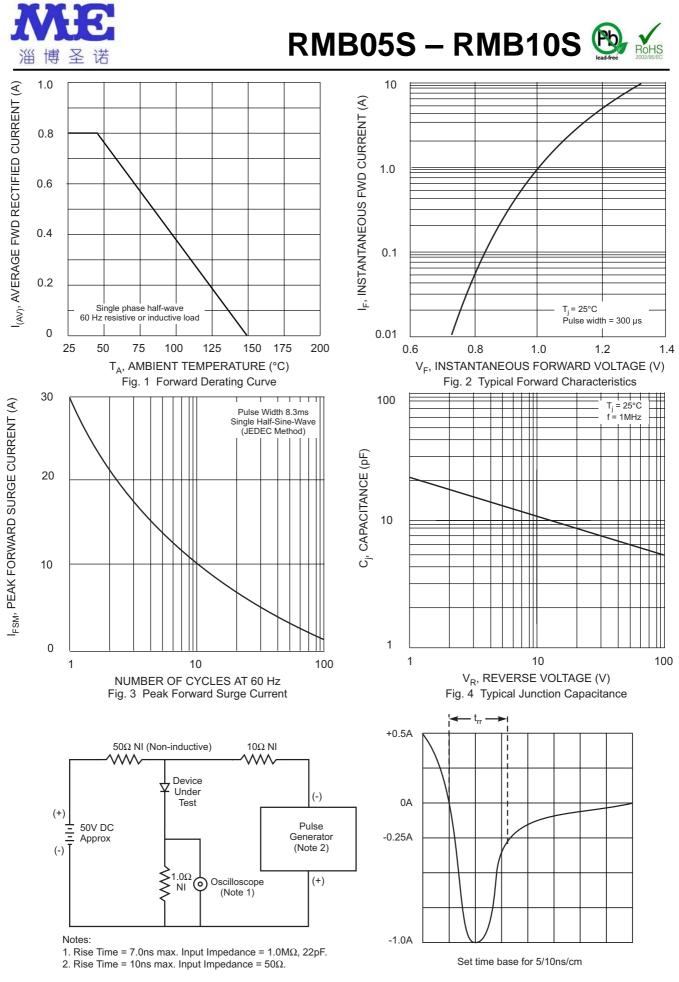
Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad.

2. Mounted on aluminum substrate PC board with 1.3mm² solder pad.

3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

4. Measured with IF = 0.5A, IR = 1.0A, IRR = 0.25A. See figure 5.

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5 Reverse Recovery Time Characteristic and Test Circuit